

RKZ6.2KL

Silicon Planar Zener Diode for Surge Absorption

REJ03G1253-0100

Rev.1.00

Nov 16, 2005

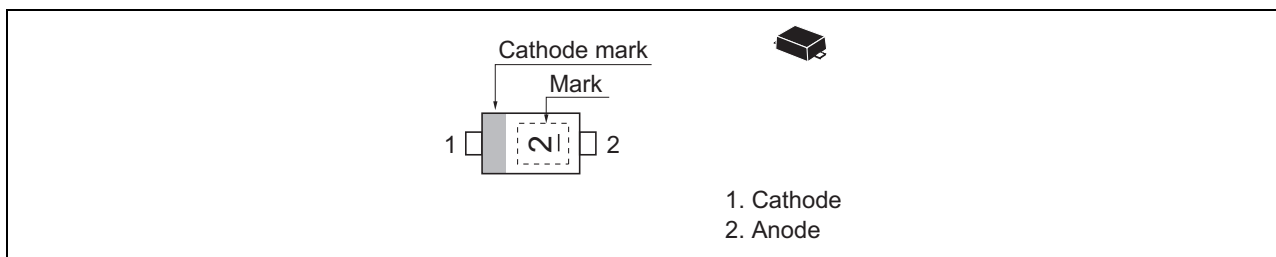
Features

- IEC61000-4-2 Contact discharge : 30kV
- Extremely small Flat Lead Package (EFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
RKZ6.2KL	2	EFP	PXSF0002ZA-A (EFP)

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd *	100	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: See Fig.2.

Electrical Characteristics

(Ta = 25°C)

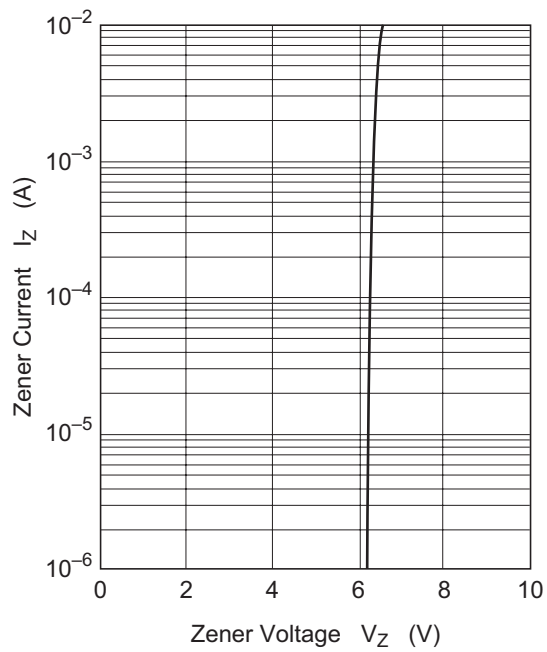
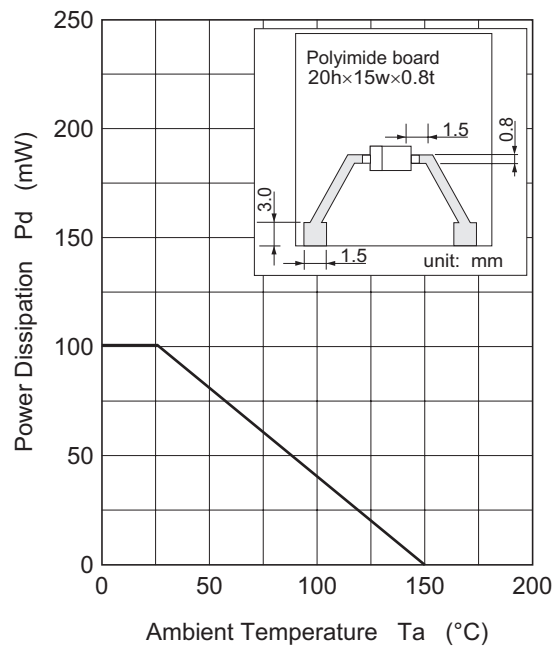
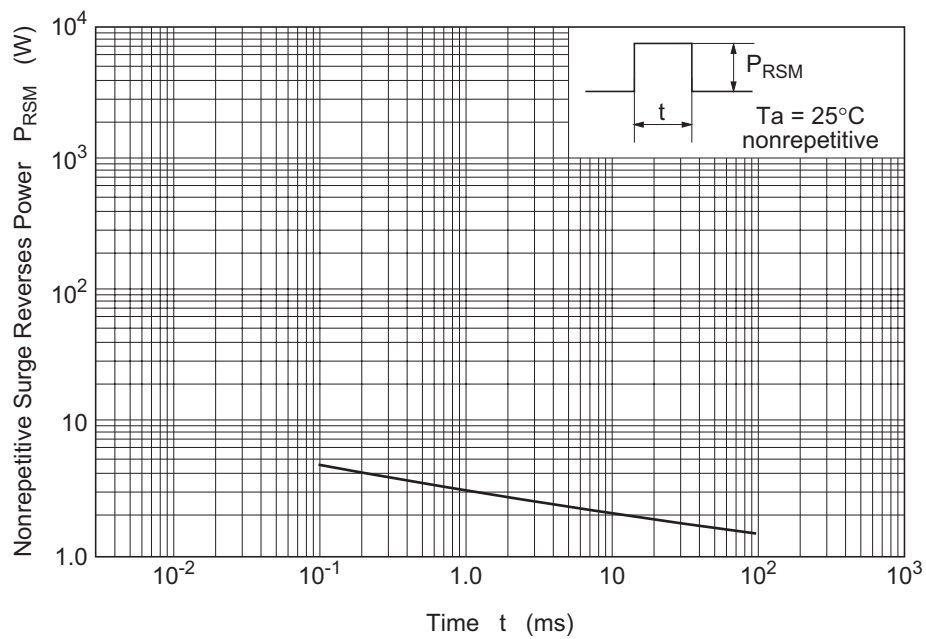
Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	V _Z	5.86	—	6.53	V	I _Z = 5 mA, 40 ms pulse
Reverse current	I _R	—	—	2	μA	V _R = 3.0 V
Dynamic resistance	r _d	—	—	50	Ω	I _Z = 5 mA
ESD-Capability * ¹	—	30	—	—	kV	C = 150 pF, R = 330 Ω, Both Forward and reverse direction 10 pulse

Notes: 1. Failure criterion ; I_R > 2 μA at V_R = 3.0 V.

2. Please do not use the soldering iron due to avoid high stress.

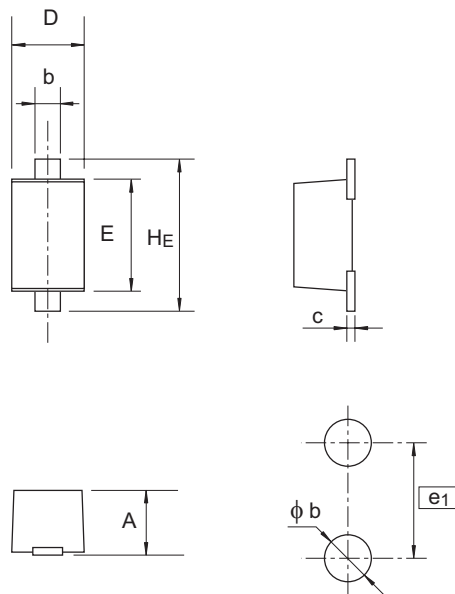
3. For EFP Package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic



Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
EFP	—	PXSF0002ZA-A	EFP / EFPV	0.0007g



Pattern of terminal position areas

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	0.44	0.47	0.50
b	0.25	0.30	0.35
c	0.08	0.13	0.18
D	0.55	0.60	0.65
E	0.75	0.80	0.85
H_E	0.95	1.00	1.05
ϕb	—	0.40	—
e_1	—	1.00	—

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